

**Average Weight: 18.83g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>1.0390</b>	<b>5.52</b>
	Silicon	7440-21-3	100.00		1.0390	
<b>Solder Bump</b>					<b>0.05127</b>	<b>0.27</b>
	Tin	7440-31-5	63.00		0.03229934	
	Lead	7439-92-1	37.00		0.01896946	
<b>Underfill</b>					<b>0.0740</b>	<b>0.40</b>
	Epoxy Resin A	9003-36-5	20.00		0.014800	
	Epoxy Resin B	25068-38-6	3.00		0.002220	
	Silica	60676-86-0	70.00		0.051800	
	Hardener	19900-65-3	7.00		0.005180	
<b>Heat Spreader</b>					<b>9.0000</b>	<b>47.79</b>
	Copper	7440-50-8	99.90		8.99100	
	Nickel	7440-02-0	0.10		0.00900	
<b>Heat Spreader Adhesive</b>					<b>0.1500</b>	<b>0.79</b>
	Organopolysiloxane mixture	N/A	100.00		0.1500	
<b>Substrate</b>					<b>7.250</b>	<b>38.50</b>
	Copper	7440-50-8	47.15	Metal layer	3.41837500	
	Nickel	7440-02-0	0.53	Metal layer	0.03842500	
	Gold	7440-57-5	0.12	Metal layer	0.00870000	
	Halogen fire retardant	N/A	5.25		0.38062500	
	Glass fiber	N/A	10.30		0.74675000	
	BT (core)	N/A	28.00		2.03000000	
	Solder mask	N/A	8.65		0.62712500	
<b>Solder Balls</b>					<b>1.26725</b>	<b>6.73</b>
	Tin	7440-31-5	95.50		1.21022375	
	Silver	7440-22-4	4.00		0.05069000	
	Copper	7440-50-8	0.50		0.00633625	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/14/06	1.0	Initial Xilinx release.
6/06/06	1.1	100% Material Declaration.
6/19/06	1.2	Updated to include Heat Spreader Adhesive data.
9/22/06	1.3	Updated component descriptions and weights.
7/20/10	1.4	Updated Heat Spreader substance description.

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